PROBE BONDING METHOD HAVING
IMPROVED CONTROL OF BONDING
MATERIAL

In assembly of probe arrays for electrical test, a problem can arise where a bonding agent undesirably wicks between probes. According to embodiments of the invention, this wicking problem is alleviated by disposing an anti-wicking agent on a surface of the probe assembly such that wicking of the bonding agent along the probes toward the probe tips is hindered. The anti-wicking agent can be a solid powder, a liquid, or a gel. Once probe assembly fabrication is complete, the anti-wicking agent is removed. In preferred embodiments, a template plate is employed to hold the probe tips in proper position during fabrication. In this manner, undesirable bending of probes caused by introduction or removal of the anti-wicking agent can be reduced or eliminated.

28 Claims, 3 Drawing Sheets